





N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C	
50V	3.5Ω @ V _{GS} = 10V	200mA	

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen- and Antimony-Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

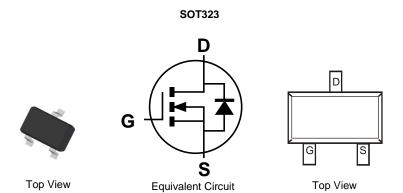
Description and Applications

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Load Switch

Mechanical Data

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208^{©3}
- Terminal Connections: See Diagram
- Weight: 0.006 grams (Approximate)



Ordering Information (Note 4)

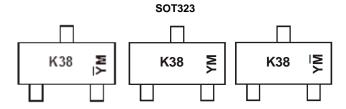
Part Number	Case	Packaging
BSS138W-7-F	SOT323	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



K38 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: H = 2020) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Year	2003		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	Р		Н	- 1	J	K	L	М	N	0	Р	R
	1	1			1			_	_			
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	50	V	
Drain-Gate Voltage (Note 5)		V_{DGR}	50	V
Gate-Source Voltage	Continuous	V _{GSS}	±20	V
Drain Current (Note 6)	Continuous	I _D	200	mA

Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	P_{D}	200	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ heta JA}$	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 7)								
Drain-Source Breakdown Voltage	BV _{DSS}	50	75		V	$V_{GS} = 0V, I_D = 250\mu A$		
Zero Gate Voltage Drain Current	I _{DSS}		_	0.5	μΑ	$V_{DS} = 50V, V_{GS} = 0V$		
Gate-Body Leakage	I _{GSS}		_	±100	nΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$		
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage	V _{GS(TH)}	0.5	1.2	1.5	>	$V_{DS} = V_{GS}, I_D = 250 \mu A$		
Static Drain-Source On-Resistance	R _{DS(ON)}		1.4	3.5	Ω	$V_{GS} = 10V, I_D = 0.22A$		
Forward Transconductance	g FS	100	_	_	mS	$V_{DS} = 25V$, $I_D = 0.2A$, $f = 1.0kHz$		
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance	C _{iss}		_	50	рF			
Output Capacitance	Coss			25	рF	$V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz$		
Reverse Transfer Capacitance	C _{rss}		_	8.0	pF			
Turn-On Delay Time	t _{D(ON)}			20	ns	$V_{DD} = 30V, I_D = 0.2A,$		
Turn-Off Delay Time	t _{D(OFF)}	_		20	ns	$R_{GEN} = 50\Omega$		

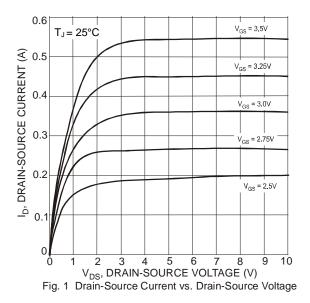
Notes: 5. Rgs \leq 20k Ω .

^{6.} Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Incorporated's suggested pad layout document, which can be found on our website at http://www.diodes.com/package-outlines.html.

7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to production testing.





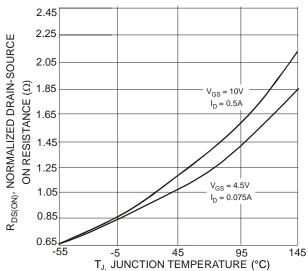


Fig. 3 Drain-Source On Resistance vs. Junction Temperature

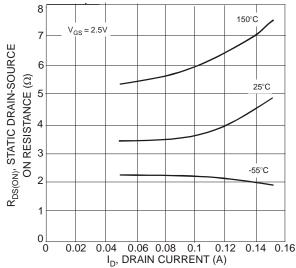
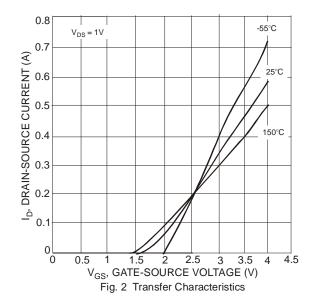


Fig. 5 Drain-Source On Resistance vs. Drain Current



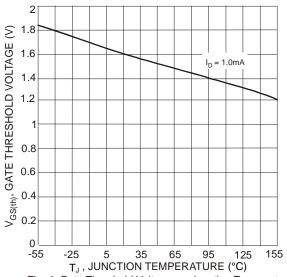


Fig. 4 Gate Threshold Voltage vs. Junction Temperature

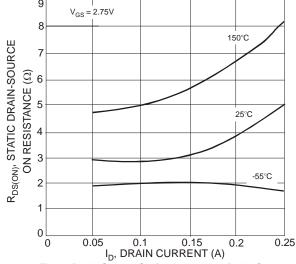
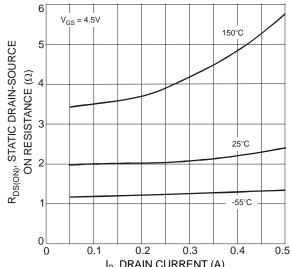
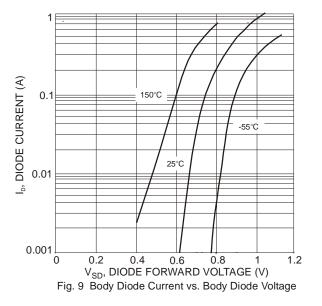


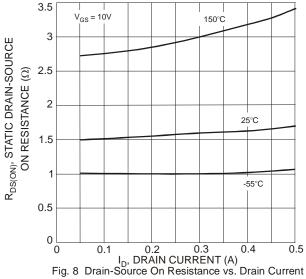
Fig. 6 Drain-Source On Resistance vs. Drain Current

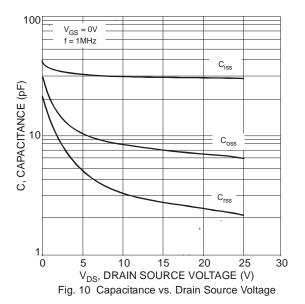




 I_{D} , DRAIN CURRENT (A) Fig. 7 Drain-Source On Resistance vs. Drain Current



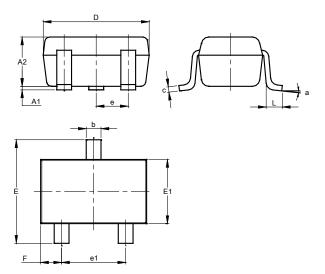






Package Outline Dimensions

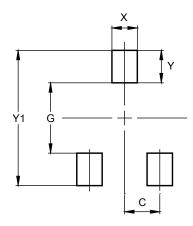
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT323							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.25	0.40	0.30				
С	0.10	0.18	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	C).650 B	SC				
e1	1.20	1.40	1.30				
F	0.375	0.475	0.425				
L	0.25	0.40	0.30				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	0.650
G	1.300
Х	0.470
Υ	0.600
Y1	2.500



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